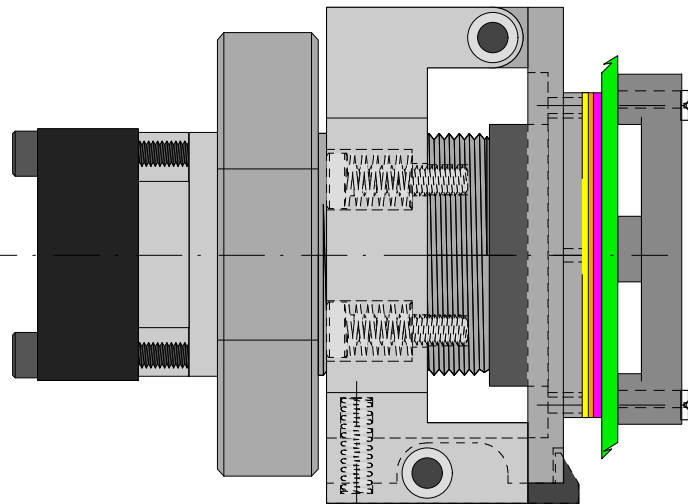
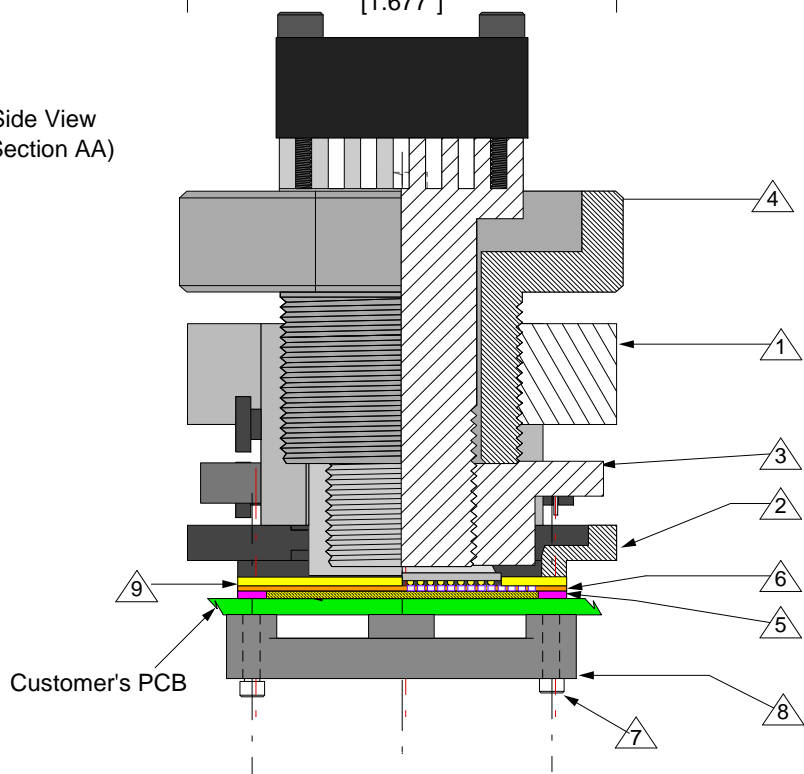


Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

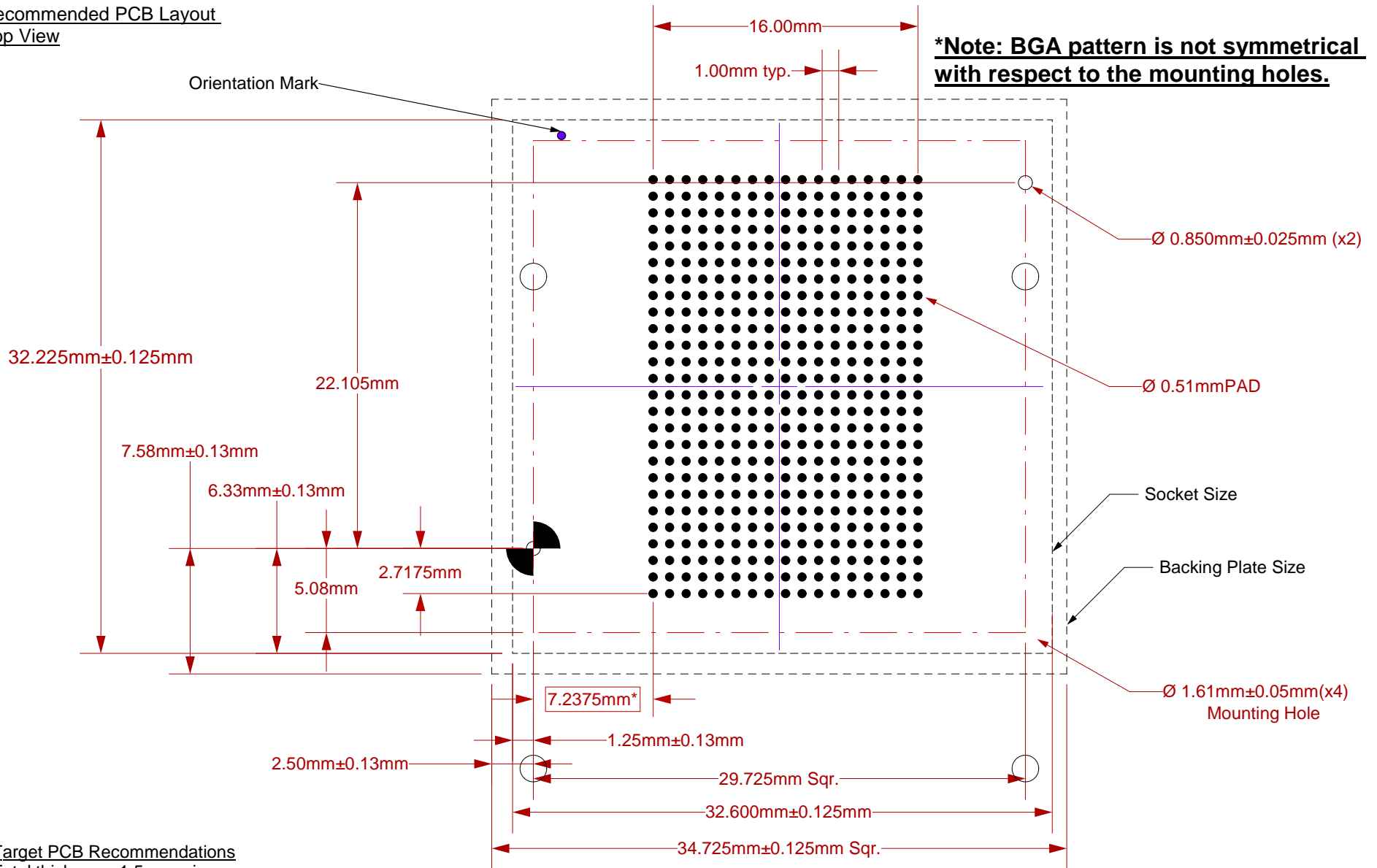
Materials:

- ① Clam Shell Lid: Black anodized 7075 Aluminum. Height = 20 mm.
- ② Socket Base: Black anodized 7075 Aluminum. Height = 6 mm.
- ③ Compression Plate: Black anodized 7075 Aluminum. Thickness = 12 mm.
- ④ Compression Screw: Clear anodized 7075 Aluminum. Height = 27 mm, Fluted Knob
- ⑤ Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- ⑥ Elastomer Guide: Non-clad FR4. Thickness = 0.75mm.
- ⑦ Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- ⑧ Backing Plate: Black anodized 7075 Aluminum
- ⑨ IC guide: Ultem.
- ⑩ Latch: Black anodized 7075 Aluminum.

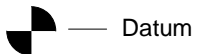
All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

	CG-BGA-4006 Drawing	Status: Released	Scale: -	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R		Date: 2/18/10
		File: CG-BGA-4006 Dwg	Modified:	


Recommended PCB Layout
Top View



Target PCB Recommendations
Total thickness: 1.5mm min.
Plating: Gold or Solder finish

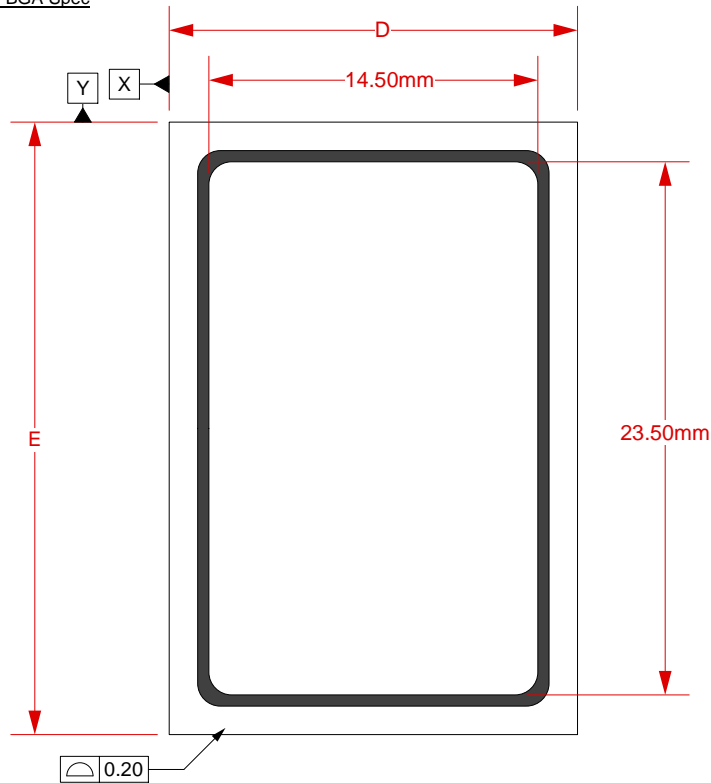


DXF DATA WILL BE PROVIDED

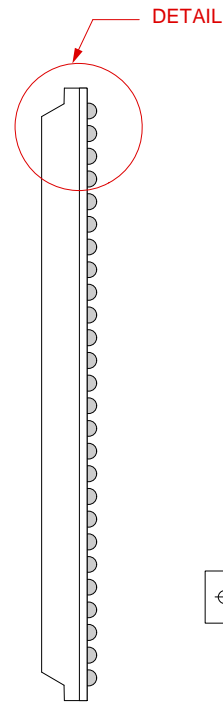
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	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R		Date: 2/18/10
		File: CG-BGA-4006 Dwg	Modified:	

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

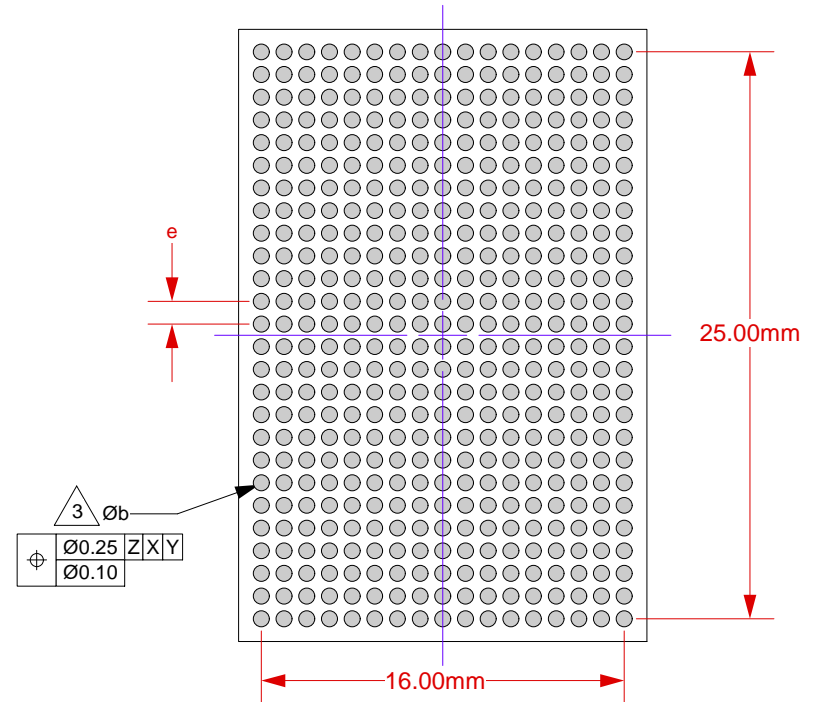
Compatible BGA Spec



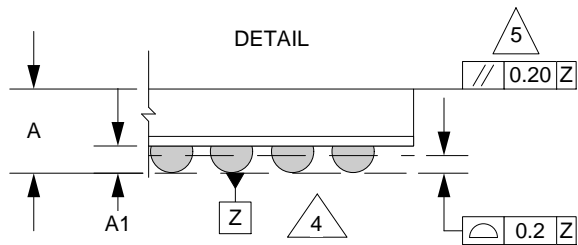
TOP VIEW



SIDE VIEW




BOTTOM VIEW



1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

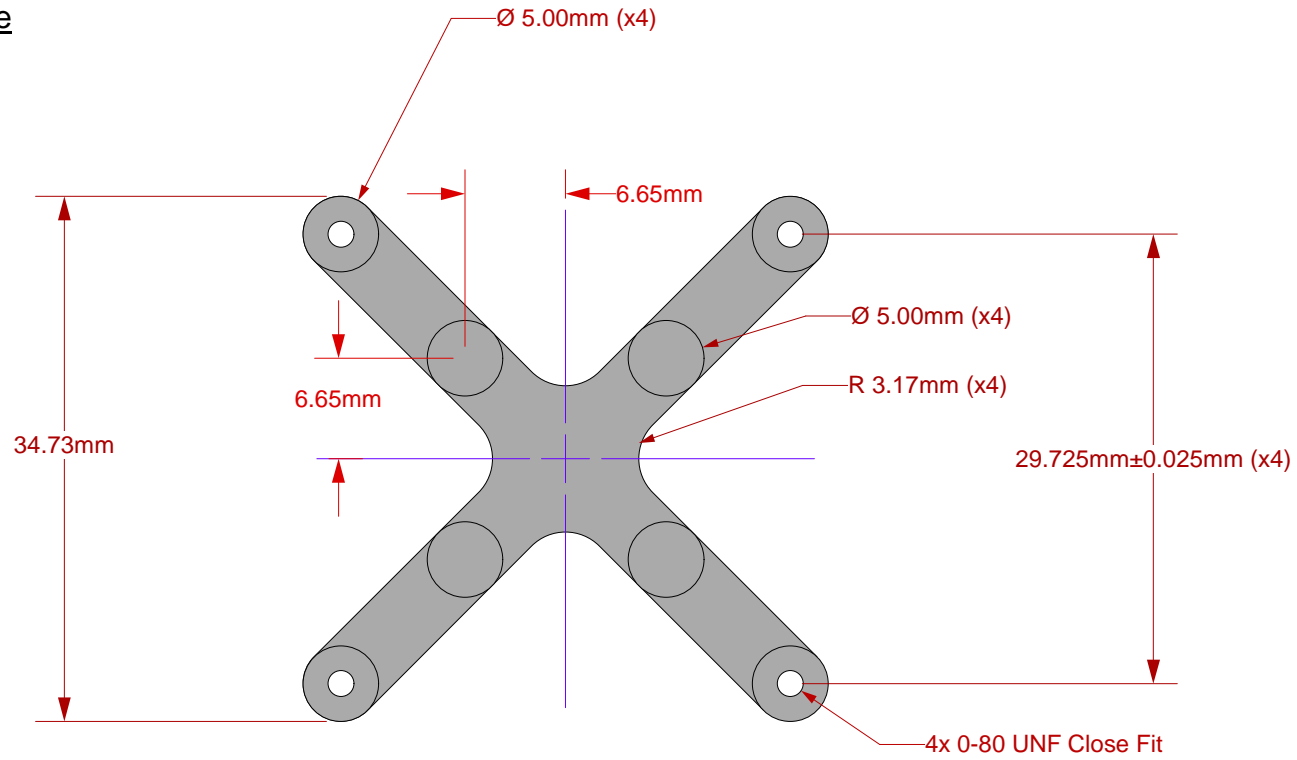
DIM	MIN	MAX
A		2.41
A1	0.4	0.6
b	0.50	0.70
D	18.00 BSC	
E	27.00 BSC	
e	1.0 BSC	

17x26 Array

 <p>© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	CG-BGA-4006 Drawing	Status: Released	Scale: -	Rev: A
	Drawing: Vinayak R		Date: 2/18/10	
	File: CG-BGA-4006 Dwg		Modified:	

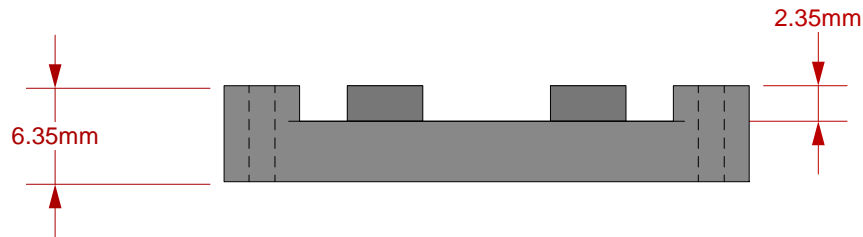
Backing Plate

Top View




Note: Backing plate holes are tapped to accept 0-80 screws.

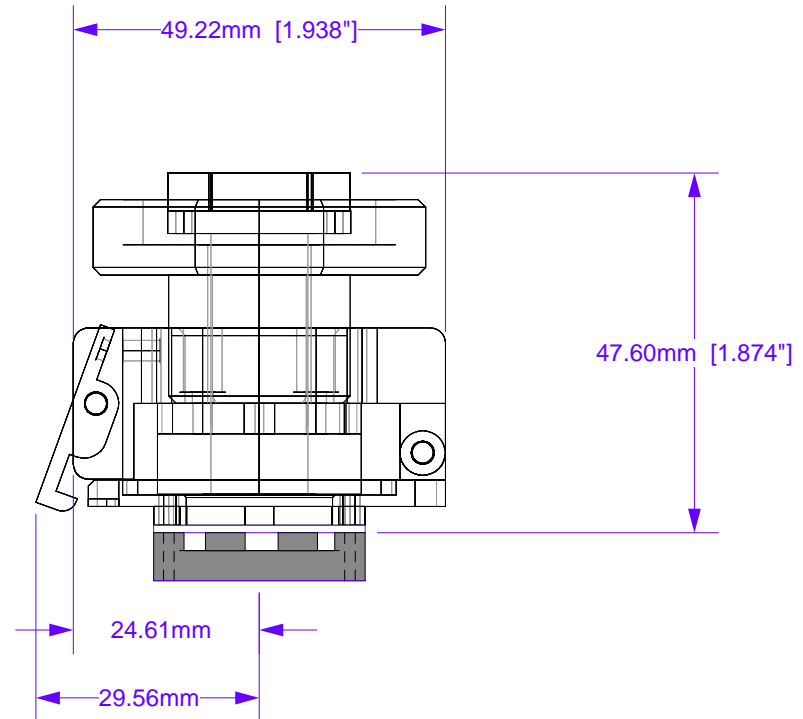
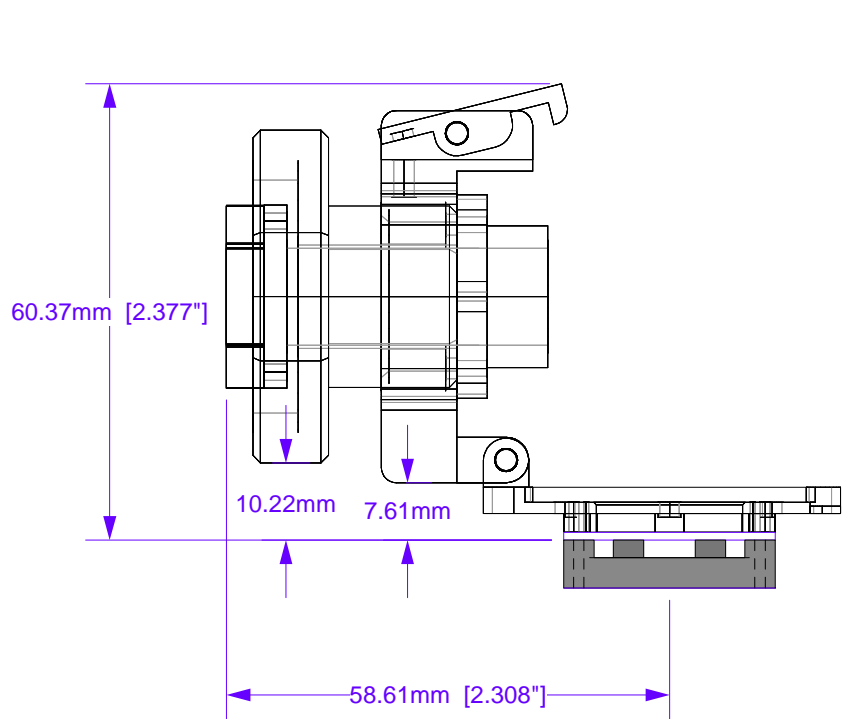
Side View




Description: Backing Plate with Insulation Plate

CG-BGA-4006 Drawing		Status: Released	Scale: -	Rev: A
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			Date: 2/18/10	
			File: CG-BGA-4006 Dwg	
			Modified:	

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)



All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)

	CG-BGA-4006 Drawing		Status: Released	Scale: 1:1	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com		Drawing: Vinayak R		Date: 2/18/10
			File: CG-BGA-4006 Dwg		Modified: